

HAT2099H

Silicon N Channel Power MOS FET Power Switching

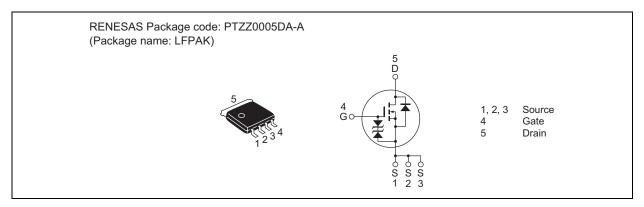
REJ03G1187-0500 (Previous: ADE-208-1432C)

> Rev.5.00 Sep 07, 2005

Features

- Capable of 4.5 V gate drive
- Low drive current
- High density mounting
- Low on-resistance $R_{DS \text{ (on)}} = 2.9 \text{ m}\Omega \text{ typ. (at } V_{GS} = 10 \text{ V)}$

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	30	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	50	А
Drain peak current	I _{D (pulse)} Note 1	200	А
Body-drain diode reverse drain current	I _{DR}	50	A
Avalanche current	I _{AP} Note 3	5	A
Avalanche energy	E _{AR} Note 3	2.5	mJ
Channel dissipation	Pch Note 2	30	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	−55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Tc = 25 °C

3. Value at Tch = 25°C, Rg \geq 50 Ω

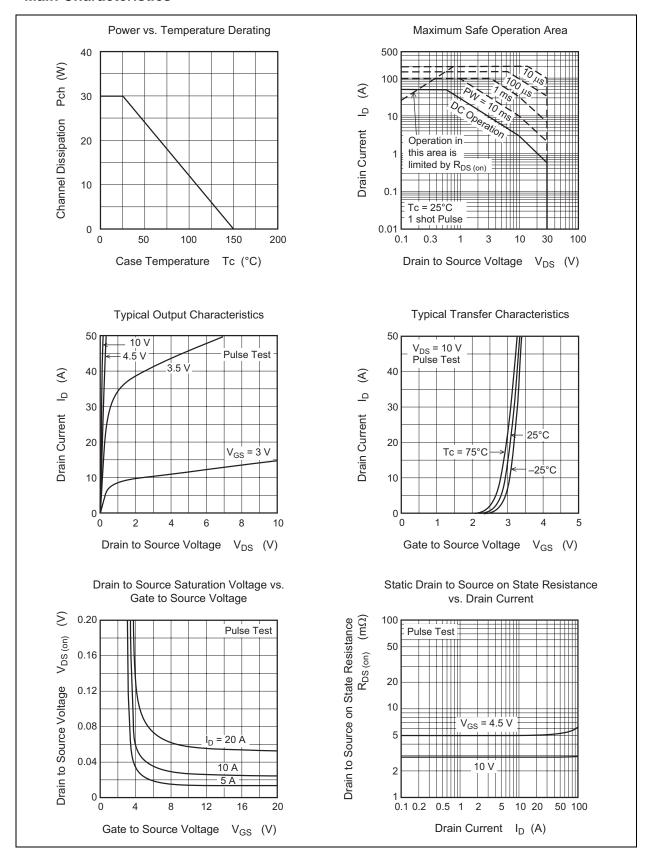
Electrical Characteristics

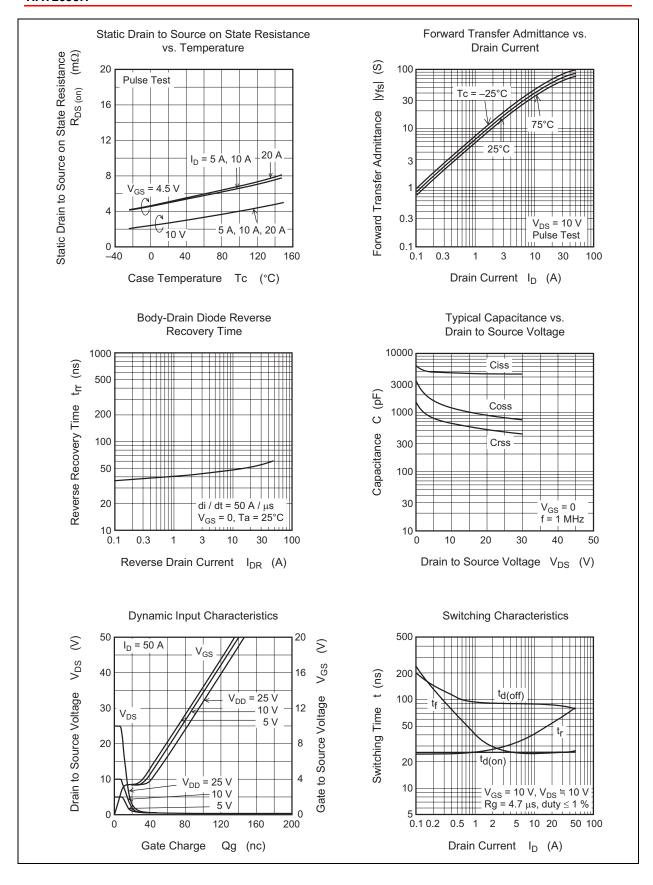
 $(Ta = 25^{\circ}C)$

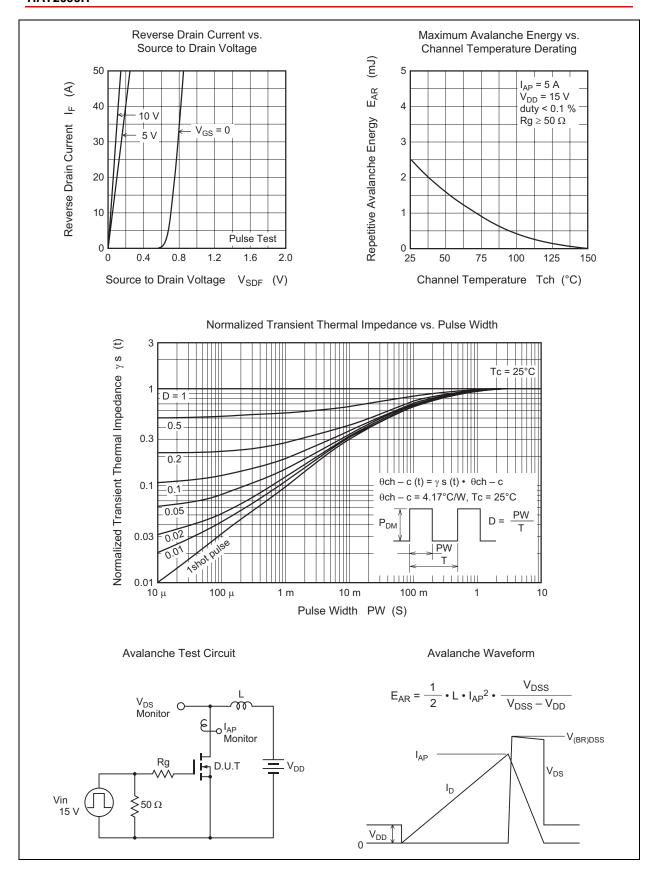
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	30			>	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR) GSS}	±20		_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_		1	μΑ	$V_{DS} = 30 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	1.0		2.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Static drain to source on state resistance	R _{DS (on)}	_	2.9	3.7	mΩ	$I_D = 25 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note 4}}$
	R _{DS (on)}	_	5.0	7.3	mΩ	$I_D = 25 \text{ A}, V_{GS} = 4.5 \text{ V}^{\text{Note 4}}$
Forward transfer admittance	y _{fs}	39	65	_	S	$I_D = 25 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 4}}$
Input capacitance	Ciss	_	4750	_	рF	V _{DS} = 10 V
Output capacitance	Coss	_	1180	_	рF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	650	_	pF	f = 1 MHz
Total gate charge	Qg	_	75		nC	V _{DD} = 10 V
Gate to source charge	Qgs	_	16	_	nC	V _{GS} = 10 V
Gate to drain charge	Qgd	_	14	_	nC	I _D = 50 A
Turn-on delay time	t _{d (on)}	_	26	_	ns	$V_{GS} = 10 \text{ V}, I_D = 25 \text{ A}$
Rise time	t _r	_	60	_	ns	$V_{DD} \cong 10 \text{ V}$
Turn-off delay time	t _{d (off)}	_	85	_	ns	$R_L = 0.4 \Omega$
Fall time	t _f	_	26	_	ns	$Rg = 4.7 \Omega$
Body-drain diode forward voltage	V_{DF}	_	0.85	0.98	V	$I_F = 50 \text{ A}, V_{GS} = 0^{\text{Note 4}}$
Body-drain diode reverse recovery time	t _{rr}	_	60		ns	I _F = 50 A, V _{GS} = 0
						$di_F/dt = 50 A/\mu s$

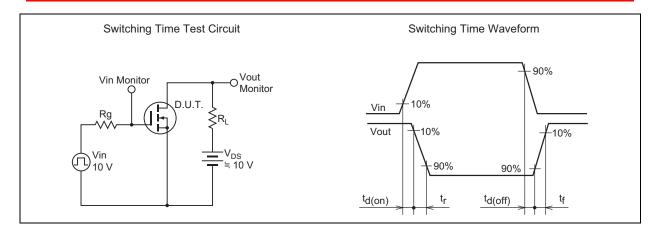
Note: 4. Pulse test

Main Characteristics

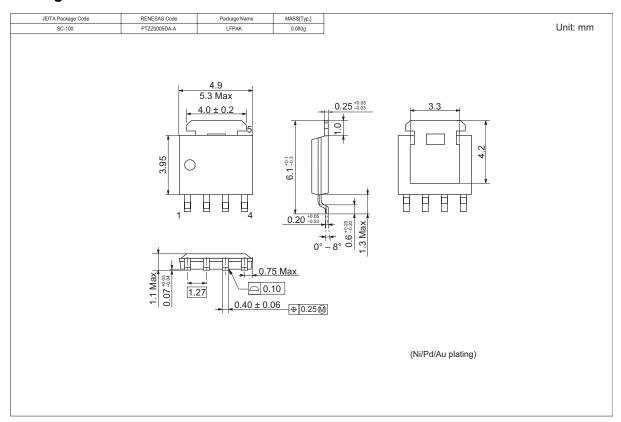








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT2099H-EL-E	2500 pcs	Taping

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